

MSF6N60

N-Channel Enhancement Mode Power MOSFET

Description

The MSF6N60 is a N-channel enhancement-mode MOSFET , providing the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness. The TO-220F package is universally preferred for all commercial-industrial applications

Features

- Low On Resistance
- Simple Drive Requirement
- Low Gate Charge
- Fast Switching Characteristic
- RoHS compliant package

Application

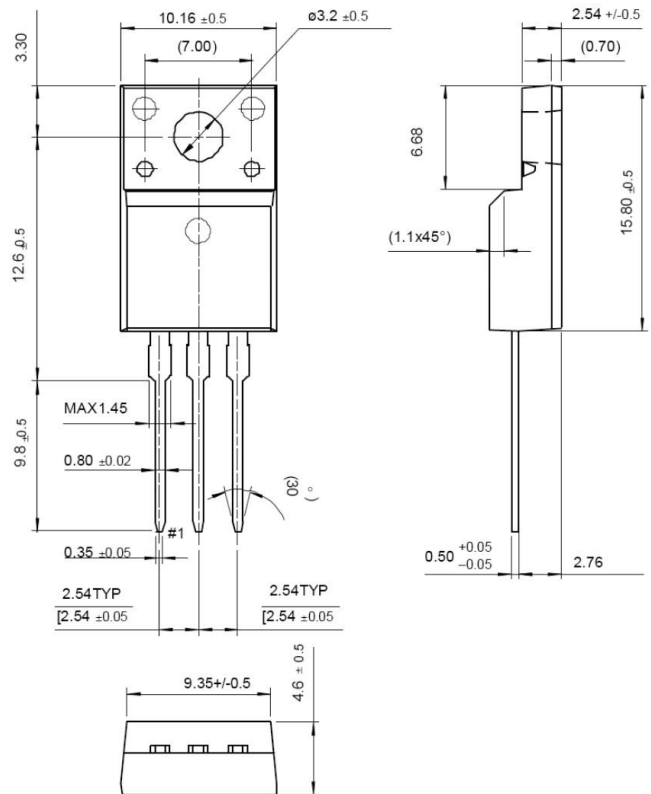
- Open Framed Power Supply
- Adapter
- STB

Packing & Order Information

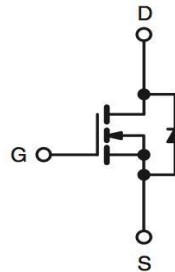
50/Tube ; 1,000/Box



**RoHS
COMPLIANT**



Graphic symbol



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V _{DSS}	Drain-Source Voltage	600	V
V _{GS}	Gate-Source Voltage	±30	V
I _D	Drain Current -Continuous (TC=25°C)	4.5	A
	Drain Current -Continuous (TC=100°C)	2.6	A
I _{DM}	Drain Current Pulsed	18	A
I _{AR}	Avalanche Current	4.5	A
E _{AS}	Single Pulsed Avalanche Energy	58.6	mJ
E _{AR}	Repetitive Avalanche Energy	10	mJ
dv/dt	Peak Diode Recovery dv/dt	4.5	V/ns

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Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C
TPKG	Maximum Temperature for Soldering @ Package Body for 10 seconds	260	°C
P_D	Total Power Dissipation (TC=25°C)	33	W
	Derating Factor above 25 °C	0.26	W/°C
T_{STG}	Operating and Storage Temperature Range	-55 to +150	°C
T_J	Storage Temperature	150	°C

Notes;

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $I_{AS}=4.5A$, $V_{DD}=50V$, $L=7mH$, $V_G=10V$, Starting $T_J=25°C$
3. $I_{SD} \leq 4.5A$, $di/dt \leq 100A/\mu s$, $V_{DD} \leq BV_{DSS}$, Starting $T_J=25°C$

Thermal Characteristics

Symbol	Parameter	Max.	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	3.75	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	

Static Characteristics

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 V$, $I_D = 250\mu A$	600	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu A$, Referenced to 25°C	--	0.6	--	V/°C
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	2.0	--	4.0	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 600 V$, $V_{GS} = 0 V$ $V_{DS} = 480 V$, $T_C = 125°C$	--	--	1 10	μA
I_{GSS}	Gate-Body Leakage Forward	$V_{GS} = \pm 30$	--	--	± 100	nA
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10 V$, $I_D = 3.0 A$	--	1.8	2.3	Ω

Dynamic Characteristics

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
$t_{d(on)}$	Turn-On Time	$V_{DS} = 300 V$, $I_D = 4.5 A$, $R_G = 10 \Omega$, $V_{GS} = 10 V$	--	9.6	--	ns
t_r	Turn-On Time		--	12.2	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	22.3	--	ns
t_f	Turn-Off Fall Time		--	14.8	--	ns

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Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
Q_g	Total Gate Charge	$V_{DS} = 300\text{ V}, I_D = 4.5\text{ A},$ $V_{GS} = 10\text{ V}$	--	16	--	nC
Q_{gs}	Gate-Source Charge		--	3.3	--	nC
Q_{gd}	Gate-Drain Charge		--	6.2	--	nC
C_{ISS}	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	700	--	pF
C_{OSS}	Output Capacitance		--	86	--	pF
C_{RSS}	Reverse Transfer Capacitance		--	20	--	pF

Source-Drain Diode						
Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
I_S		$V_D = V_G = 0$	--	--	4.5	A
I_{SM}		$V_S = 1.3\text{ V}$	--	--	18	
V_{SD}		$I_S = 4.5\text{ A}, V_{GS} = 0\text{ V}$	--	--	1.5	V
t_{rr}		$I_F = 4.5\text{ A}, V_{GS} = 0\text{ V}$	--	320	--	ns
Q_{rr}		$di_F/dt = 100\text{ A}/\mu\text{s}$	--	2.7	--	μC

Notes;

1. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$

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■ Characteristics Curve

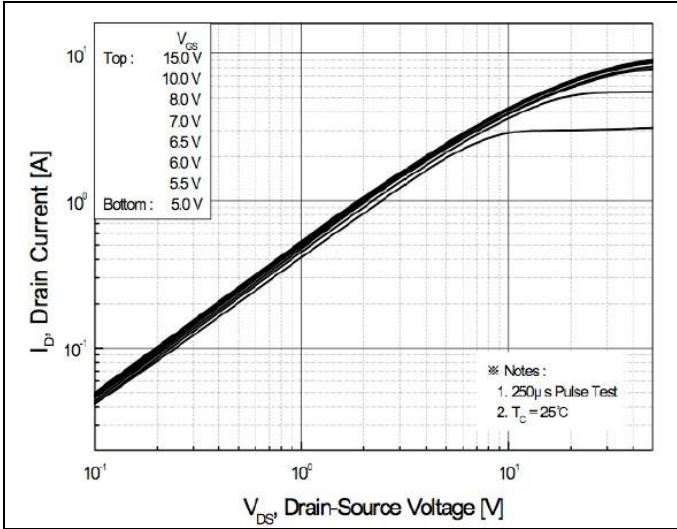


FIG.1-ON REGION CHARACTERISTICS

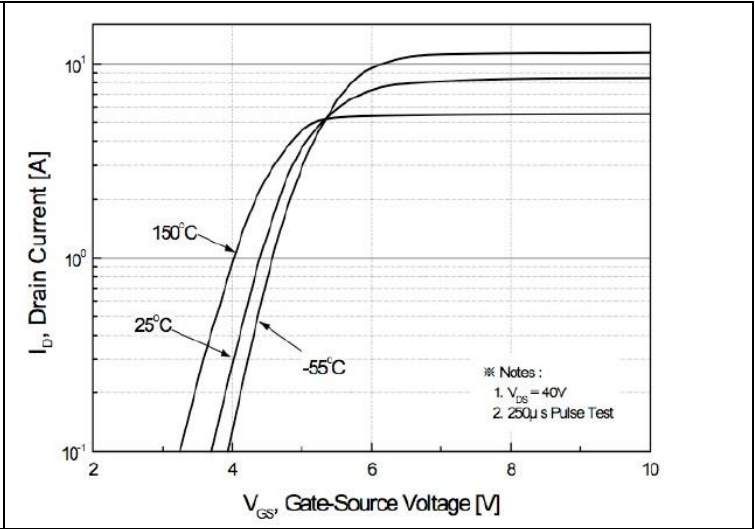


FIG.2-TRANSFER CHARACTERISTICS

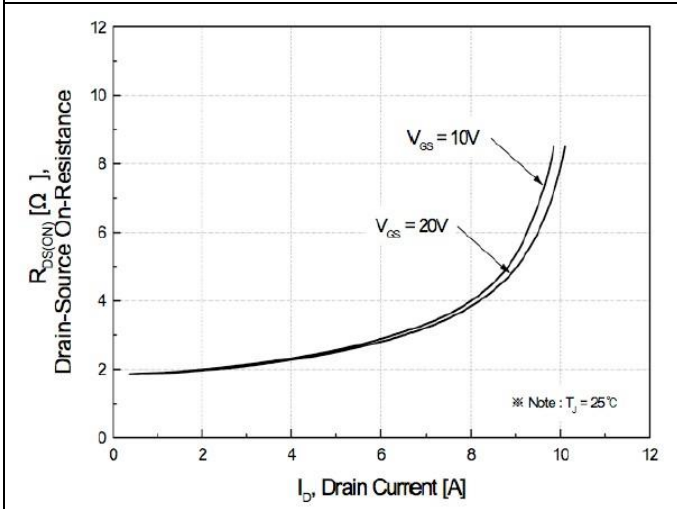


FIG.3-ON RESISTANCE VARIATION VS DRAIN CURRENT AND GATE VOLTAGE

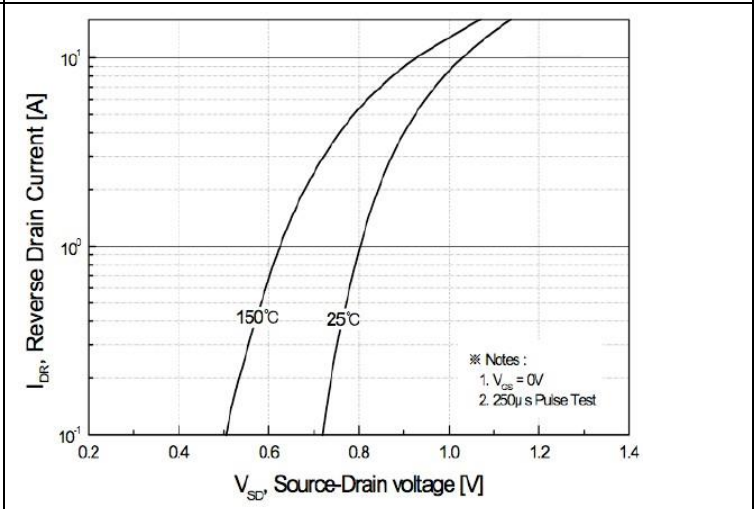


FIG.4-BODY DIODE FORWARD VOLTAGE VARIATION WITH SOURCE CURRENT AND TEMPERATURE

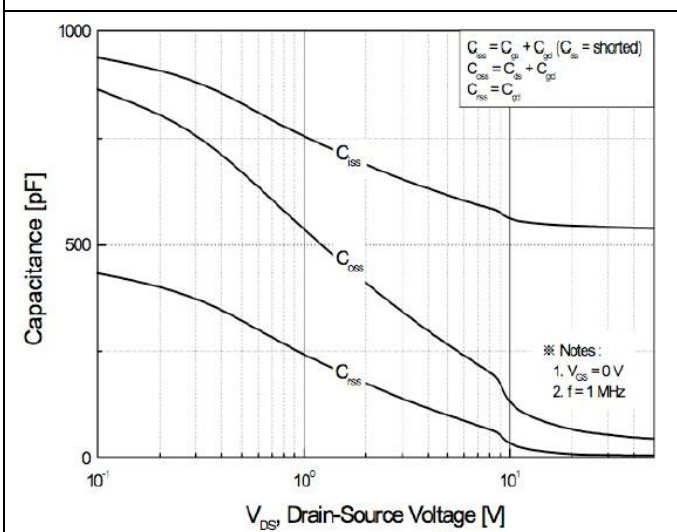


FIG.5-CAPACITANCE CHARACTERISTICS

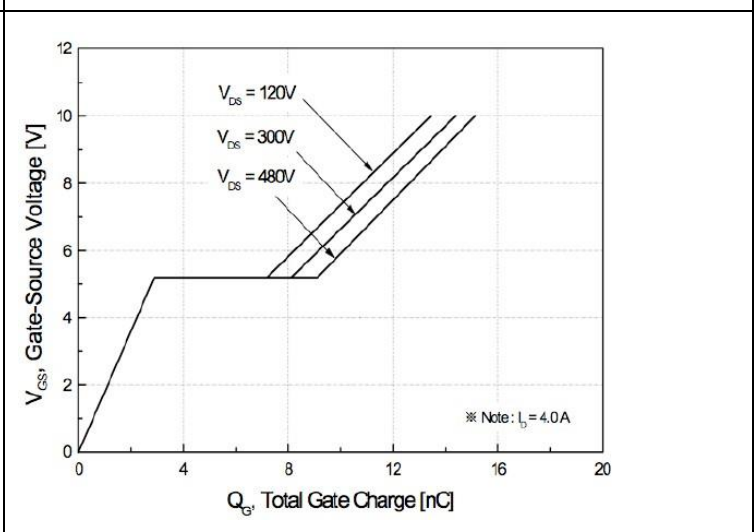


FIG.6-GATE CHARGE CHARACTERISTICS

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■ Characteristics Curve

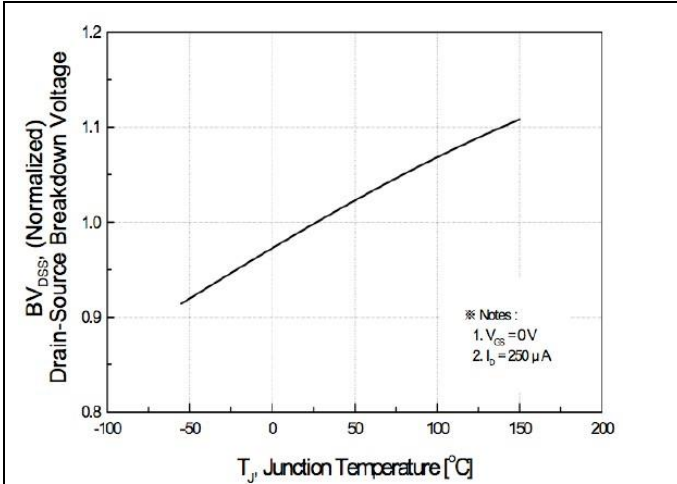


FIG.7-BREAKDOWN VOLTAGE VARIATION VS TEMPERATURE

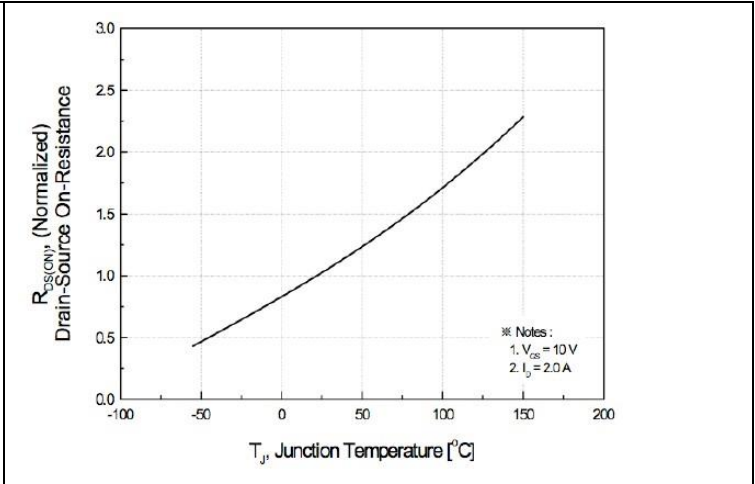


FIG.8-ON-RESISTANCE VARIATION VS TEMPERATURE

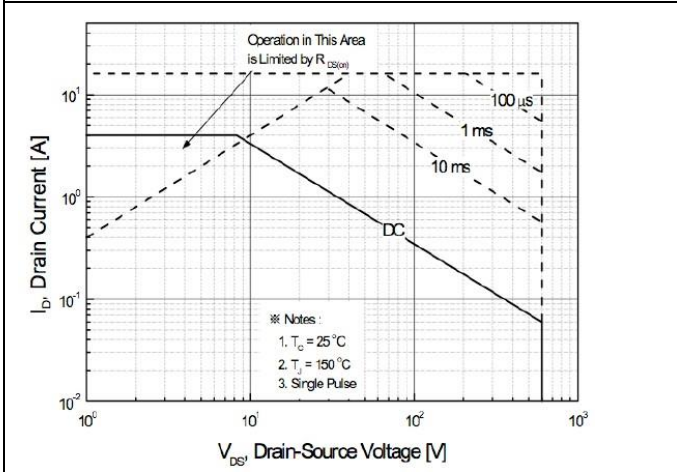


FIG.9-MAXIMUM SAFE OPERATING AREA

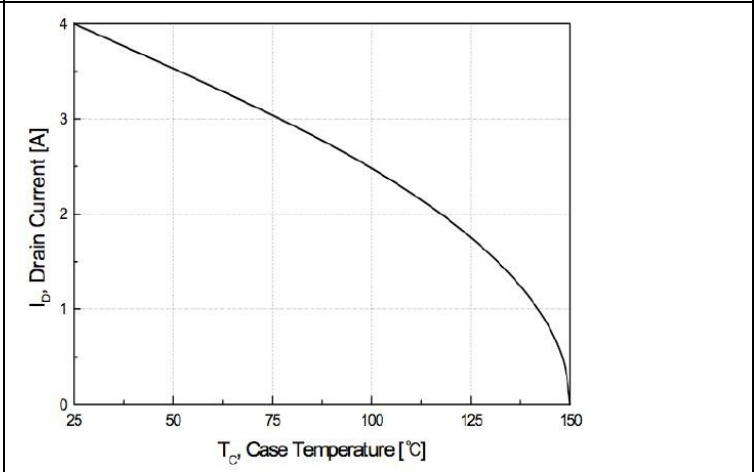


FIG.10-MAXIMUM DRAIN CURRENT VS CASE TEMPERATURE

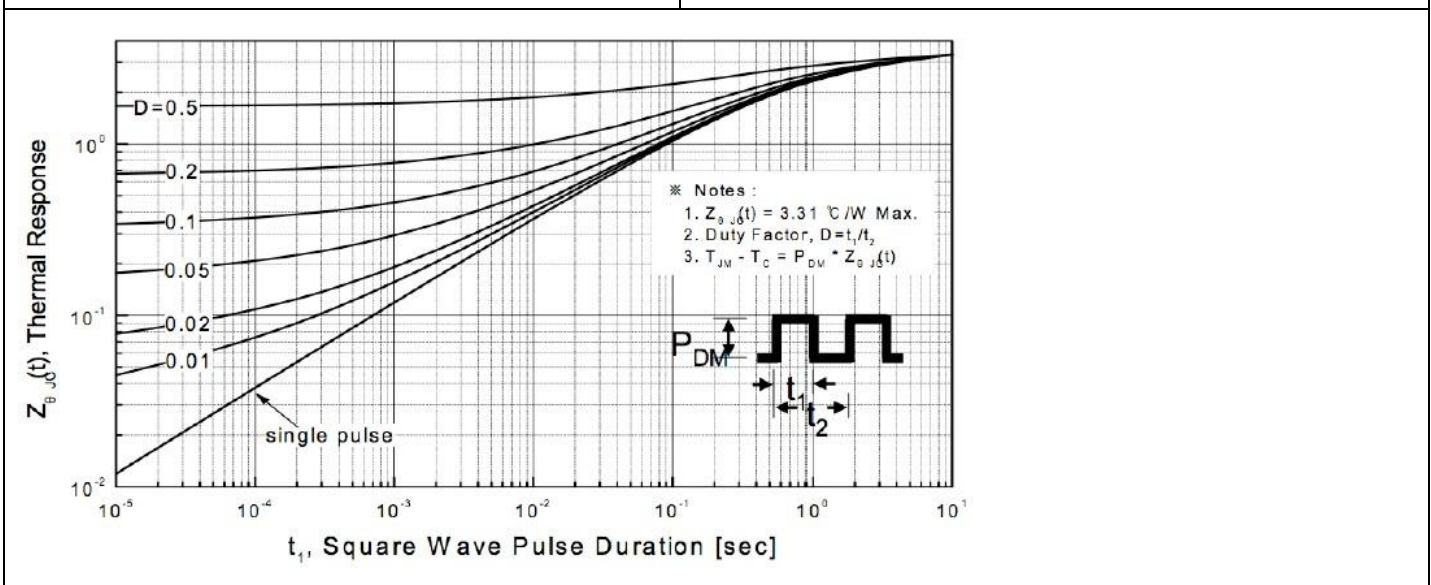


FIG.11-TRANSIENT THERMAL RESPONSE CURVE

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